Renesas RA Family

EK-RA6M3 Example Project Bundle

Introduction

This document describes the contents of the Example Project Bundle for the EK-RA6M3 kit. The Example Projects contained within the bundle show how to write code for the various Renesas Flexible Software Package (FSP) modules supported by the EK-RA6M3 kit.

Flexible Software Package is an optimized software package designed to provide easy to use, scalable, high-quality software for embedded system design. The primary goal is to provide lightweight, efficient drivers that meet common use cases in embedded systems. FSP code quality is enforced by peer reviews, automated requirements-based testing, and automated static analysis. FSP provides uniform and intuitive APIs that are well documented. Each module is supported with detailed user documentation including example code. FSP modules can be used on any MCU in the RA family, provided the MCU has any peripherals required by the module. FSP modules can be configured at build-time to optimize the size of the module for the feature set required by the application.

Supported Kit

EK-RA6M3

Supported FSP Version

FSP v5.2.0

Supported Toolchains

For the latest version of each Integrated Development Environment (IDE) and toolchain listed below, please refer to the FSP release notes

- e² studio with GCC Arm Embedded
- Keil MDK with Arm compiler toolchain
- IAR EWARM with IAR toolchain for Arm

1. Using the Example Projects

To use EK-RA6M3 Example Projects, follow the steps mentioned in the following documents:

- Example Project Usage Guide
  https://github.com/renesas/ra-fsp-examples/blob/master/example_projects/Example%20Project%20Usage%20Guide.pdf
- e² studio AC6 porting Guide
  https://en-support.renesas.com/knowledgeBase/19375553

Users who are new to the FSP are recommended to refer to the section **Starting Development** > **Tutorial: Your First RA MCU Project – Blinky** in the RA FSP Documentation prior to attempting to program or debug an example project.

2. List of Example Projects Supported on Different Toolchains in the Bundle

The following table lists example projects supported by each IDE. These are ready to import using the import process for each IDE.

Note:

1. Additional example projects other than those mentioned above, may be available in the example project repository. However, they are supported with older version of FSP. Please refer the example_projects/version_info_table.md file in the repository to identify the appropriate FSP version for the example project of interest.
2. All projects supported by e^2 studio/GCC are supported with e^2 studio/AC6 via port from GCC.

Table 1. IDE Support for the Example Project

	IDE Support		
Example Project	**e² studio/GCC**	**IAR**	**Keil MDK**
FileX_block_media_qspi_LevelX	Supported		
FileX_block_media_sdmmc	Supported		
FileX_exFAT_block_media_sdmmc	Supported		
NetX_dhcpv4_client	Supported		
NetX_dhcpv4_server	Supported		
NetX_dhcpv6_client	Supported		
NetX_dhcpv6_server	Supported		
NetX_ftp_client	Supported		
NetX_ftp_server	Supported		
NetX_https_client	Supported		
NetX_smtp_client	Supported		
NetX_snmp_agent	Supported		
NetX_sntp_client	Supported		
NetX_wifi	Supported		
USBX_dfu	Supported		
USBX_hcdc_acm	Supported		
USBX_hhid	Supported		
USBX_hmsc	Supported		
USBX_host_hub	Supported		
USBX_hprn	Supported		
USBX_huvc	Supported		
USBX_paud	Supported		
USBX_pcdc_acm	Supported		
USBX_phid	Supported		
USBX_pmsc	Supported		
USBX_pprn	Supported		
_quickstart	Supported		
acmphs	Supported		
adc	Supported		
adc_gpt_periodic_sampling	Supported		
agt	Supported	Supported	Supported
audio_playback_pwm	Supported		
aws_https_client	Supported		
cac	Supported		
can	Supported		
can_fifo	Supported		
cpp	Supported		

	IDE Support		
Example Project	**e² studio/GCC**	**IAR**	**Keil MDK**
crc	Supported		
dac	Supported		
dma_spi	Supported		
dmac	Supported	Supported	Supported
doc	Supported		
elc	Supported		
ethernet	Supported	Supported	Supported
flash_hp	Supported	Supported	Supported
freertos	Supported	Supported	Supported
gpt	Supported	Supported	Supported
gpt_input_capture	Supported		
icu	Supported	Supported	Supported
iic_master	Supported		
iic_slave	Supported	Supported	Supported
iwdt	Supported		
jpeg_codec	Supported		
kint	Supported		
lpm	Supported		
lvd	Supported		
mbed_crypto	Supported		
pdc	Supported		
poeg	Supported		
ptp	Supported		
qspi	Supported		
qspi_blockmedia_usb_composite	Supported		
rtc	Supported	Supported	Supported
sci_i2c	Supported		
sci_spi	Supported		
sci_uart	Supported	Supported	Supported
sdhi	Supported		
spi	Supported	Supported	Supported
ssi	Supported		
ssi_slave	Supported		
usb_composite	Supported		
usb_hcdc	Supported		
usb_hhid	Supported		
usb_hmsc	Supported		
usb_hmsc_baremetal	Supported		
usb_hvnd	Supported		
usb_multiport	Supported		
usb_pcdc	Supported		
usb_pcdc_with_freertos	Supported		
usb_phid	Supported		
usb_pmsc	Supported		
usb_pvnd	Supported		
vee_flash	Supported		
wdt	Supported	Supported	Supported
wifi	Supported		
wifi_on_chip_udp_freertos	Supported		

Website and Support

Visit the following URLs to learn about key elements of the RA family, download components and related documentation, and get support.

RA Product Information	renesas.com/ra
RA Product Support Forum	renesas.com/ra/forum
RA Flexible Software Package	renesas.com/FSP
Renesas Support	renesas.com/support

Revision History

		Description	
Rev.	**Date**	**Page**	**Summary**
1.00	Apr.23.20	—	First release document.
1.01	Jun.1.20	—	Examples updated for IAR.
1.02	Jul.09.20	—	Updated for FSP v1.2.0.
1.03	Jul.24.20	—	Updated for new EPs supported on FSP v1.2.0.
1.04	Aug.12.20	NA	Package updated to include this document.
1.05	Sep.03.20	—	Updated for FSP v1.3.0.
1.06	Sep.14.20	—	This revision includes changes to the code files. There are no changes to this document.
1.07	Oct.12.20	—	Support for FSP v2.0.0.
1.08	Oct.23.20	—	Updated support for IAR and Keil, added VEEPROM.
1.09	Nov.02.20	—	Support for FSP v2.1.0.
1.10	Dec.01.20	—	Support for FSP v2.2.0.
1.11	Feb.02.21	—	Support for FSP v2.3.0.
1.12	Mar.10.21	—	Support for USB COMPOSITE, USB HVND, and USB PVND.
1.13	Apr.06.21	—	Added support for FSP v2.4.0.
1.14	Apr.23.21	—	Added AWS HTTPS CLIENT.
1.15	May.03.21	—	Added support for FSP v3.0.0.
1.16	May.13.21	—	Added support for FSP v3.0.0 (2).
1.17	May.27.21	—	Added support for FSP v3.0.0 (3).
1.18	Jun.16.21	—	Added support for FSP v3.0.0 (4).
1.19	Jul.12.21	—	Added support for FSP v3.1.0 (1).
1.20	Jul.26.21	—	Added support for FSP v3.1.0 (2).
1.21	Aug.30.21	—	Added support for FSP v3.1.0 (3).
1.22	Sep.10.21	—	Added support for FSP v3.2.0.
1.23	Sep.30.21	—	Added support for FSP v3.3.0 (2).
1.24	Oct.20.21	—	Added support for FSP v3.4.0 (2).
1.25	Dec.20.21	—	Added support for FSP v3.5.0 (2).
1.26	Mar.21.22	—	Added support for FSP v3.6.0.
1.27	Apr.11.22	—	Added support for FSP v3.6.0 (2).
1.28	Jul.18.22	—	Added support for FSP v3.8.0 (1).
1.29	Aug.11.22	—	Added support for FSP v3.8.0 (2).
1.30	Sep.20.22	—	Added support for FSP v4.0.0.
1.31	Oct.17.22	—	Added support for FSP v4.0.0 (2).
1.32	Nov.14.22	—	Added support for FSP v4.1.0 (1).
1.33	Dec.01.22	—	Added support for FSP v4.1.0 (2).
1.34	Jan.10.23	—	Added support for FSP v4.2.0 (1).
1.35	Mar.24.23	—	Added support for FSP v4.3.0 (2).
1.36	Apr.28.23	—	Added support for FSP v4.3.0 (3).
1.37	Jun.01.23	—	Added support for FSP v4.4.0 (2).
1.38	Jul.17.23	—	Added support for FSP v4.5.0 (1).
1.39	Sep.18.23	—	Added support for FSP 4.5.0 (2).
1.40	Sep.26.23	—	Added support for FSP v4.6.0 (1).
1.41	Oct.23.23	—	Added support for FSP v4.6.0 (2).
1.42	Nov.06.23	—	Added support for FSP v5.0.0 (2).
1.43	Dec.05.23	—	Added support for FSP v5.0.0 (3).
1.44	Dec.19.23	—	Added support for FSP v5.1.0 (2).

1.45	Jan.29.24	—	Added support for FSP v5.1.0 (4).
1.46	Mar.11.24	—	Added support for FSP v5.2.0 (1).
1.47	Mar.21.24	—	Added support for FSP v5.2.0 (2).

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.
2. Processing at power-on

   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.
3. Input of signal during power-off state

   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.
4. Handling of unused pins

   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.
5. Clock signals

   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.
6. Voltage application waveform at input pin

   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
7. Prohibition of access to reserved addresses

   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
8. Differences between products

   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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